

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5507750

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIH-YAO KUO	05/03/2019
CHIN-KAI SUN	05/03/2019
CHUN-LUNG CHU	05/03/2019
WEI-CHENG LIU	05/03/2019
RECEIVING PARTY DATA	
Name:	HTC CORPORATION
Street Address:	NO. 23, XINGHUA ROAD, TAOYUAN DISTRICT,
City:	TAOYUAN CITY
State/Country:	TAIWAN
Postal Code:	330
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16403616
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	05/06/2019
Total Attachments: 2	
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ASSIGNMENT

WHEREAS,

1.Chih-Yao Kuo
3.Chun-Lung Chu

2.Chin-Kai Sun
4.Wei-Cheng Liu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **HEAT DISSIPATION MODULE AND ELECTRONIC DEVICE**

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, 1. HTC Corporation
of No. 23, Xinghua Road, Taoyuan District, Taoyuan City 330,
Taiwan (R.O.C.)

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chih-Yao Kuo Date: 5/3 2019

Sole or First Joint Inventor: **Chih-Yao Kuo**

Signature: Chin-Kai Sun Date: 5/3 2019

Second Joint Inventor (if any): **Chin-Kai Sun**

Signature: CHUN-LUNG CHU Date: 5/3 2019

Third Joint Inventor (if any): **Chun-Lung Chu**

Signature: Wei-Cheng Liu Date: 5/3 2019

Fourth Joint Inventor (if any): **Wei-Cheng Liu**